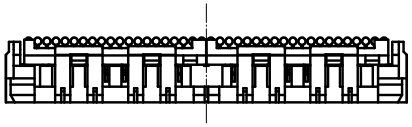
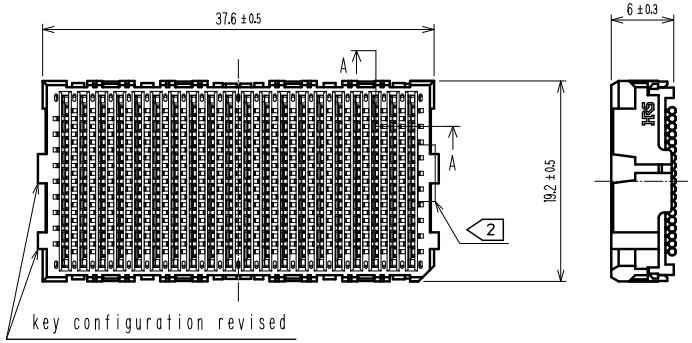
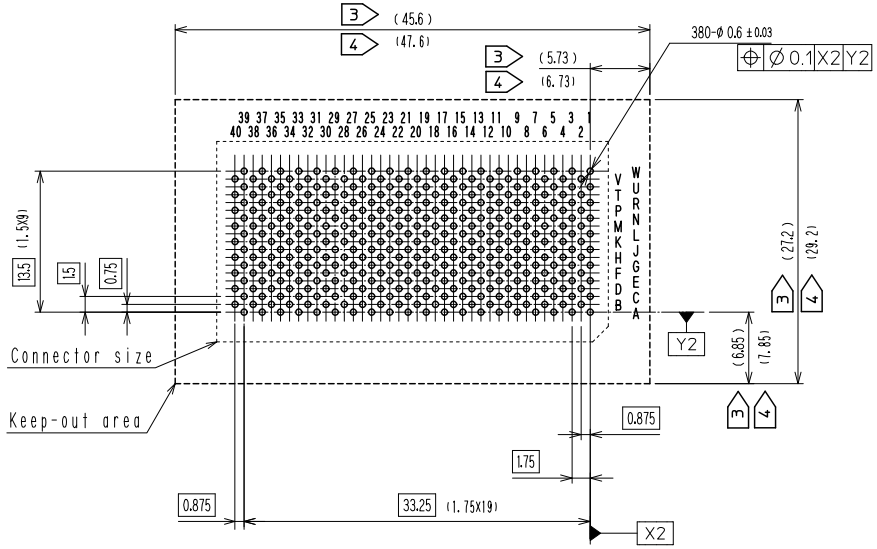
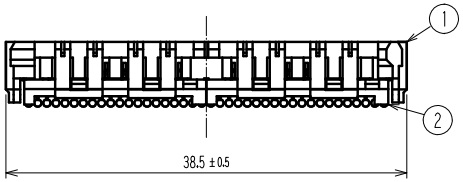
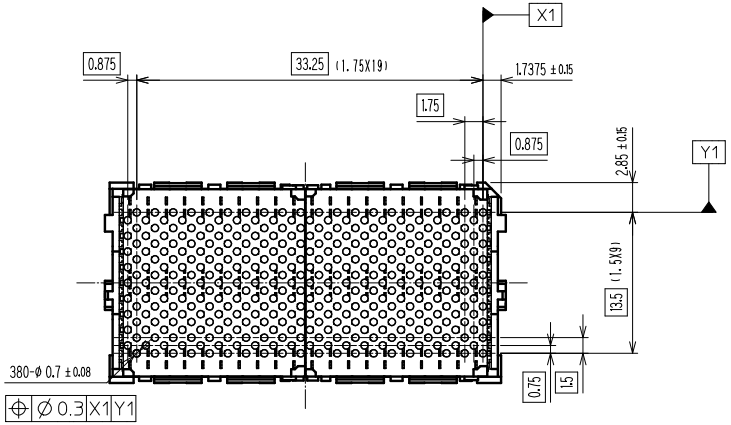






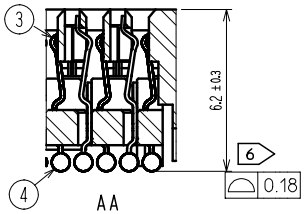
Recommended PCB Footprint
(Connector Side)





NOTE

1. IT3D receptacle to be mated and unmated with IT3-200P-**HC(**).
2. Lot no. is marked on top of the connector.
3. Minimum clearance for all devices.
4. Minimum clearance for sensitive devices.
5. More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
6. Maximum coplanarity of the ball field is 0.18 mm.
7. Standard package of 72pcs are packaged in a carton box.
8. This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
9. This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

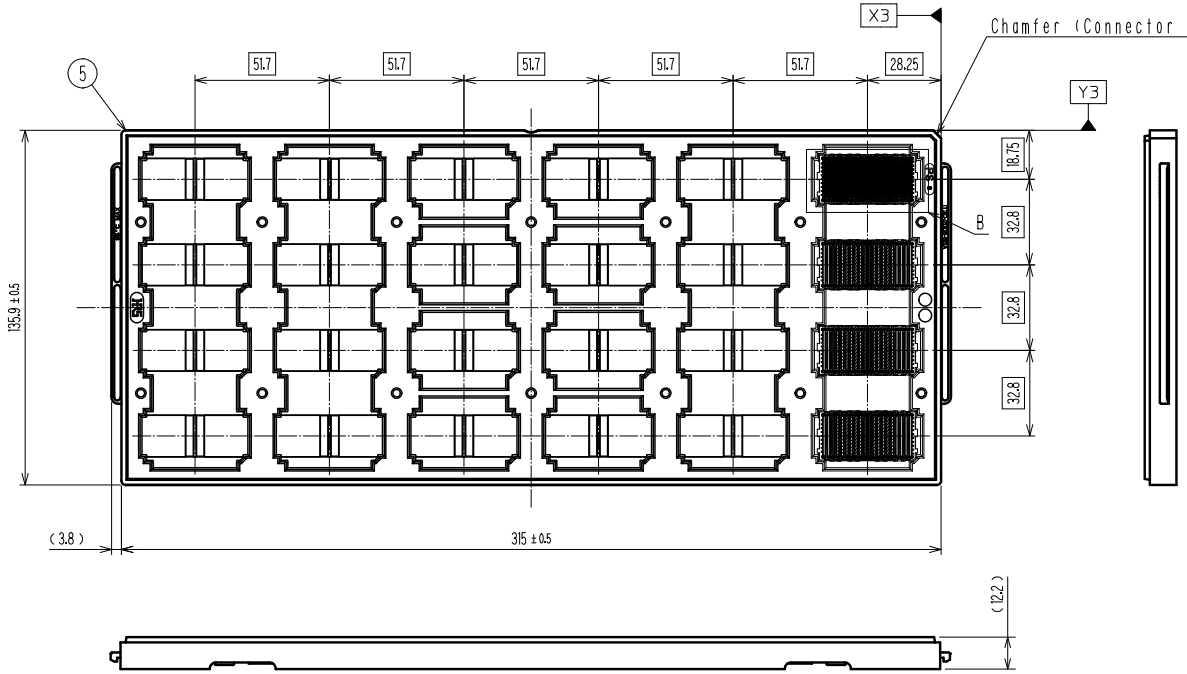


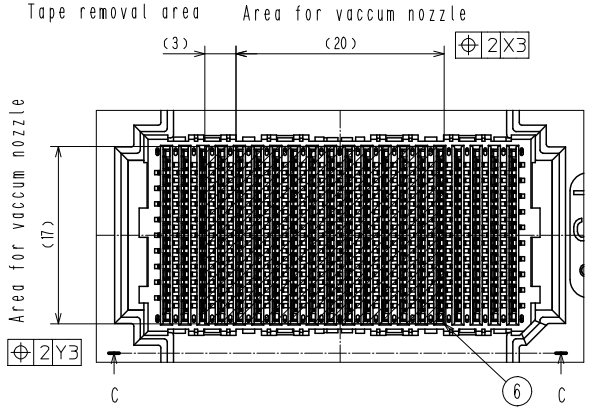
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
3	Copper alloy	Contact area : Nickel(1.5μm) + Gold(0.76μm) Other area : Nickel(1.5μm)	6	NORMEX	TAPE , WHITE
2	LCP	BLACK , UL94V-0	5	HIPS	TRAY , BLACK
1	LCP	GRAY	4	TIN	Sn(96.5)-Ag(3)-Cu(0.5)

UNITS mm	SCALE 2:1	REV	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE

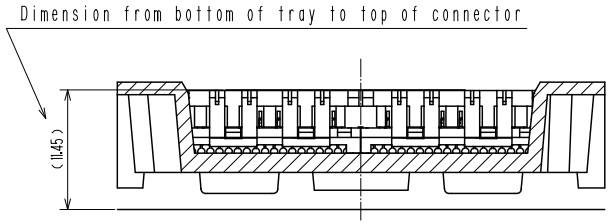
HIROSE ELECTRIC CO., LTD.

APPROVED : T. MATSUO	02/08/2010	DRAWING NO.	EDC3-156951-04	
CHECKED : T. MATSUO	02/08/2010	PART NO.	IT3D-200S-BGA(39)	
DESIGNED : T. KIKUCHI	02/05/2010			
DRAWN : T. KIKUCHI	02/05/2010	CODE NO.	CL636-0003-8-39	1/2





B



CC

HRS	DRAWING NO.	EDC3-156951-04
	PART NO.	IT3D-200S-BGA(39)
	CODE NO.	CL636-0003-8-39 △2

FORM NO. 229-21